

SOT2120-1

LFBGA358, low-profile, fine-pitch ball grid array package, 358 terminals, 0.65 mm pitch, 15 mm x 15 mm x 1.21 mm body

2 June 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA358
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-03-2017
Manufacturer package code	MV-A301087-00

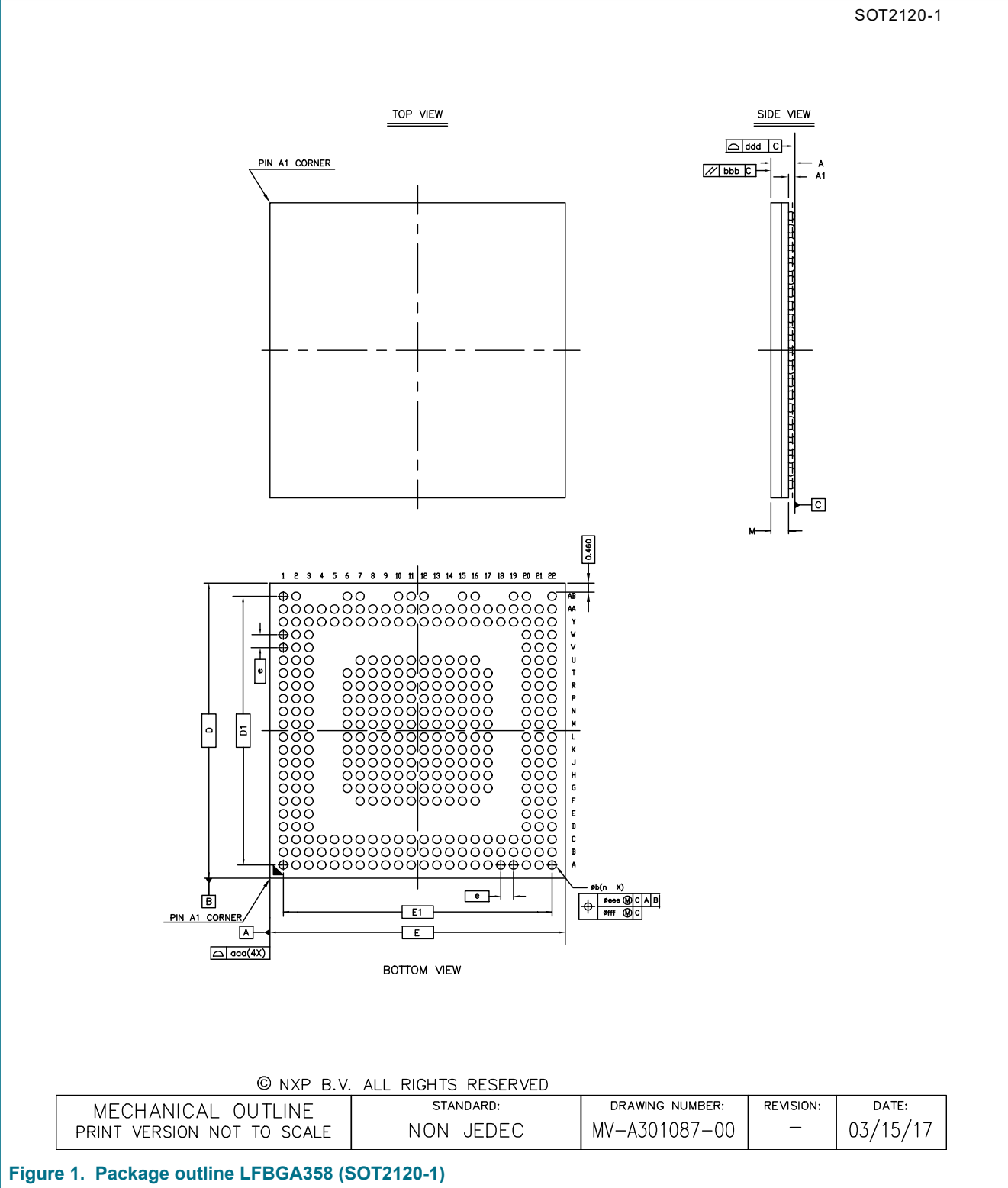
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	14.9	15	15.1	mm
package width	14.9	15	15.1	mm
package height	1.14	1.21	1.28	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	358	-	



LFBGA358, low-profile, fine-pitch ball grid array package, 358 terminals, 0.65 mm pitch, 15 mm x 15 mm
x 1.21 mm body

2 Package outline



LFBGA358, low-profile, fine-pitch ball grid array package, 358 terminals, 0.65 mm pitch, 15 mm x 15 mm
x 1.21 mm body

SOT2120-1

		Symbol	Common Dimensions		
			MIN.	NOM.	MAX.
Body Size:	X	E	14.90	15.00	15.10
	Y	D	14.90	15.00	15.10
Ball Pitch :	e		0.65		
Total Thickness :	A		1.14	1.21	1.28
Body Thickness :	M		0.84	0.89	0.94
Stand Off :	A1		0.27	0.32	0.37
Ball Width :	b		0.38	0.43	0.48
Package Edge Tolerance :	aaa		0.10		
Mold Flatness :	bbb		0.10		
Coplanarity:	ddd		0.12		
Ball Offset (Package) :	eee		0.15		
Ball Offset (Ball) :	fff		0.08		
Ball Count :	n		358		
Edge Ball Center to Center :	X	E1	13.65		
	Y	D1	13.65		

© NXP B.V. ALL RIGHTS RESERVED

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: MV-A301087-00	REVISION: —	DATE: 03/15/17
--	------------------------	----------------------------------	----------------	-------------------

Figure 2. Package outline note LFBGA358 (SOT2120-1)

3 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

1	Package summary	1
2	Package outline	2
3	Legal information	4